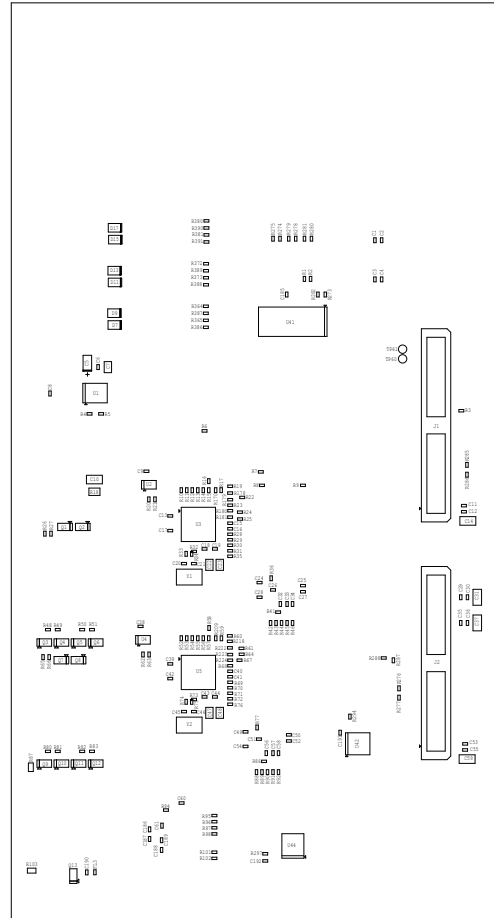



PROC084 E3 ASSEMBLY TOP

ASSEMBLY NOTES:-

- 1 - All MSL components should be baked as per JEDEC standard.
- 2 - PCB should be baked at 120 degree for 8 hours.
- 3 - Board assembly must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- 4 - These assemblies are ESD sensitive, ESD precautions shall be observed.
- 5 - These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 6 - Provide serial numbers to the assembled boards for identification.
- 7 - The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

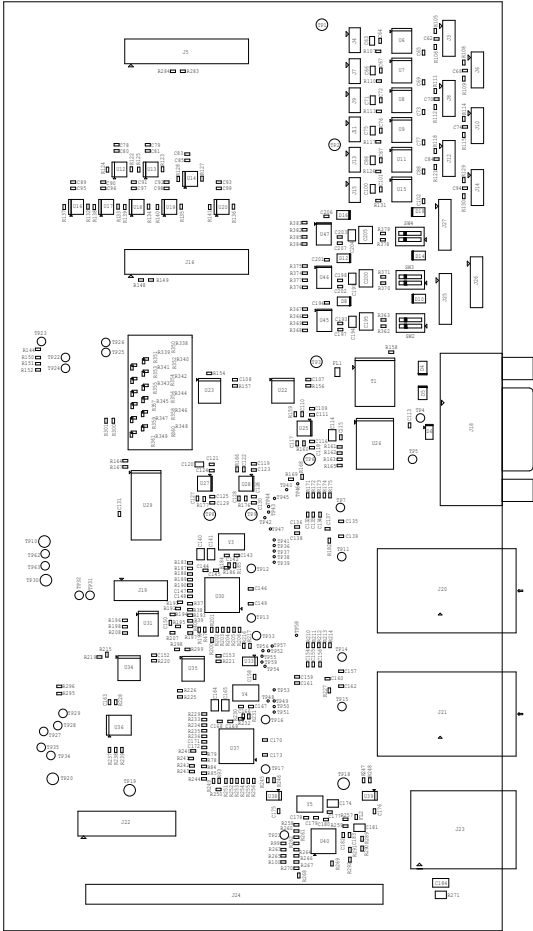



		TEXAS INSTRUMENTS		PROC084
BOARD NAME: J7X GESI EXP BRD		REV: E3	DESCRIPTION: ASSEMBLY TOP	
SCALE: 1		DATE: 04/09/2019	SHEET 01 OF 02	

PROC084 E3 ASSEMBLY BOTTOM

ASSEMBLY NOTES:-

- 1 - All MSL components should be baked as per JEDEC standard.
- 2 - PCB should be baked at 120 degree for 8 hours.
- 3 - Board assembly must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- 4 - These assemblies are ESD sensitive, ESD precautions shall be observed.
- 5 - These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 6 - Provide serial numbers to the assembled boards for identification.
- 7 - The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.



		TEXAS INSTRUMENTS		PROC084
BOARD NAME: J7X GESI EXP BRD		REV: E3	DESCRIPTION: ASSEMBLY BOTTOM	
SCALE: 1		DATE: 04/09/2019	SHEET 02 OF 02	